

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



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MOV



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PLED

## **XC6228DXX2VR-G(MS)**

**Product specification**

## 产品描述

XC6228DXX2VR-G(MS) 系列是一组低压差 (LDO) 转换器, 具有 1.2V 至 5.5V 宽电压输入范围、低压差、低功耗和小型化封装的等特性。

XC6228DXX2VR-G(MS) 低至 2uA 低静态电流特性, 特别适合用于电池供电、长时间待机系统设备应用, 能帮助降低系统设备的 待机功耗, 有效延长待机时间和电池使用寿命。

XC6228DXX2VR-G(MS) 有带 EN 使能引脚的版本可选, 将 EN 脚拉低可进入关断模式, 此关断模式下静态电流可降至仅 100nA (典型值)。XC6228DXX2VR-G(MS) 系列支持输出电容采用陶瓷电容器, 在 1.2V 至 5.5V 的宽输入电压范围内和整个输出负载电流 0mA-300mA 范围内稳定工作。

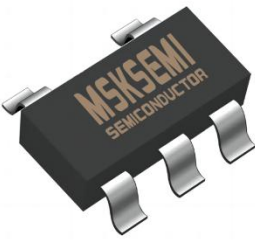
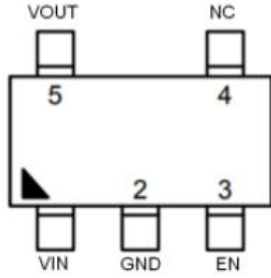
## 产品特性

- 2uA 静态电流 (无负载)
- $\pm 2\%$  输出电压精度
- 300mA 输出电流能力
- 100nA 关断电流 (可选版本)
- 宽范围输入电压: 1.2V 至 5.5V
- 低压差: 0.18V ( $V_o=3.3V/I_o=300mA$  条件下)
- 支持固定输出电压: 1.2V, 1.5V, 1.8V, 2.5V, 2.8V, 3.0V, 3.3V
- 支持陶瓷电容或者钽电容
- 限流保护
- 过温保护

## 产品应用

- 手持式、电池供电设备
- 低功耗微处理器
- 笔记本电脑、掌上型电脑和 PDA
- 无线通讯设备
- 音频/视频设备
- 车载导航系统

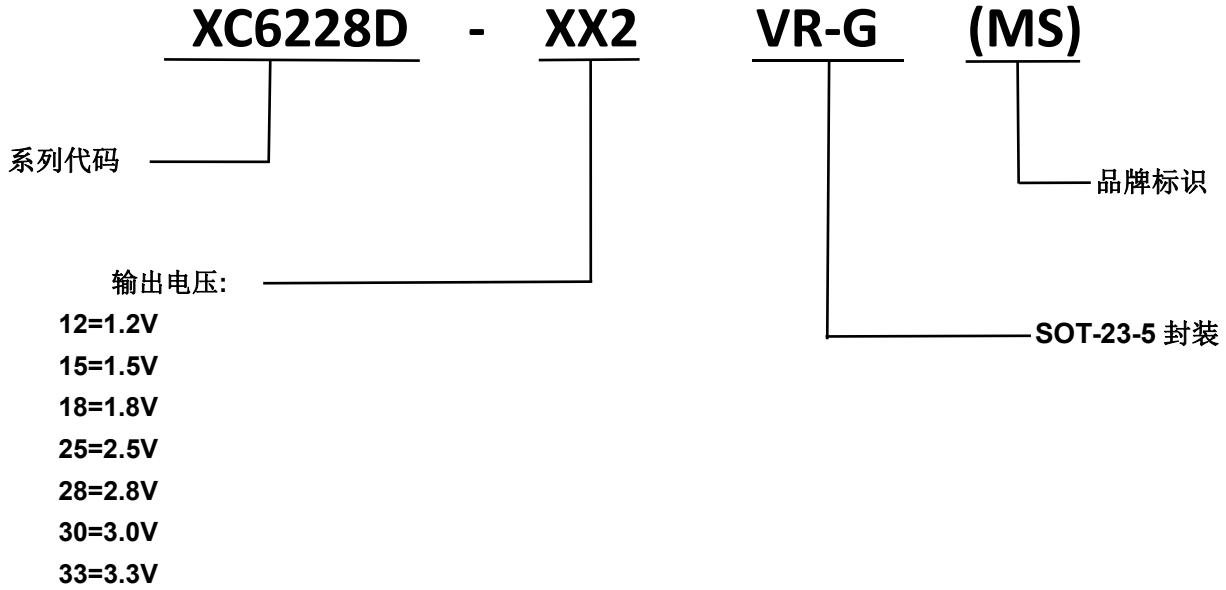
## 封装脚位图

SOT-23-5	Pin Configurations
	

## 引脚功能描述

脚位号	名称	功能描述
2	GND	接地
5	VOUT	电压输出端口
1	VIN	电源输入端口
3	EN	使能控制
4	NC	浮空脚

产品信息



XC6228D122VR-G(MS)	XC6228D152VR-G(MS)
<b>AADB</b> ****	<b>AADG</b> ****
XC6228D182VR-G(MS)	XC6228D252VR-G(MS)
<b>AABB</b> ****	<b>AAET</b> ****
XC6228D282VR-G(MS)	XC6228D302VR-G(MS)
<b>AAC6</b> ****	<b>AADC</b> ****
XC6228D332VR-G(MS)	
<b>AAC7</b> ****	

典型应用电路

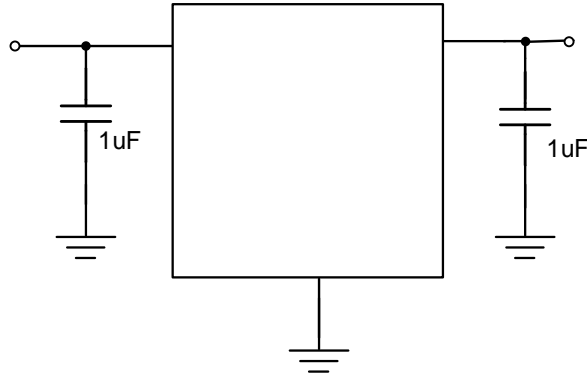


图 1: 固定输出应用电路

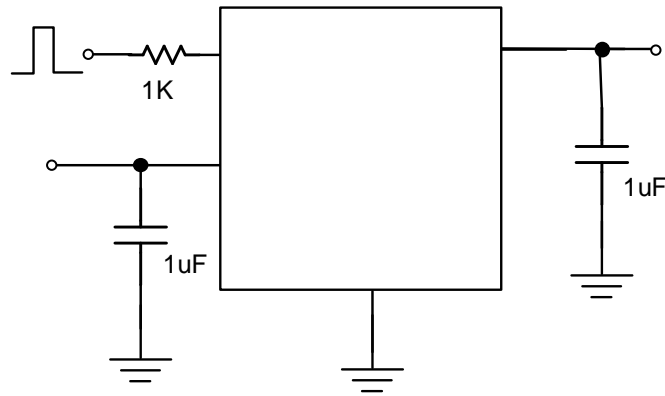


图 2: 带使能脚的固定输出应用电路

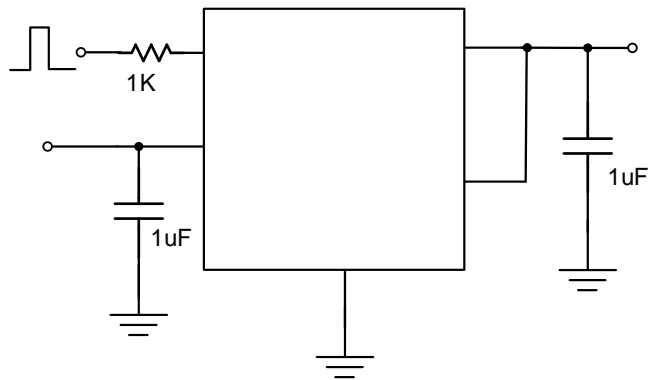


图 3: 固定输出带使能功能和输出电压检测功能之应用电路



**最大耐压值** (Note 1)

VIN 至 GND	-0.3V to 7V
VOUT, EN 至 GND	-0.3V to 6V
VOUT 至 VIN	-6V to 0.3V
封装热阻 (Note 2)	
$\theta_{JA}$	200 °C /W
引脚焊锡温度 (Soldering, 10 sec.)	260 °C
结点温度	150 °C
存储温度范围	-60 °C to 150 °C
ESD 静电	
HBM	2KV
MM	200V
CDM	2KV

**建议应用条件**

输入电压 VIN	1.2V to 5.5V
应用结温范围	-40 °C to 125 °C
应用环温范围	-40 °C to 85 °C

**电气特性**

 ( $V_{IN} = 5V$ ,  $V_{EN} = 5V$   $T_A = 25^\circ C$  除另有说明外)

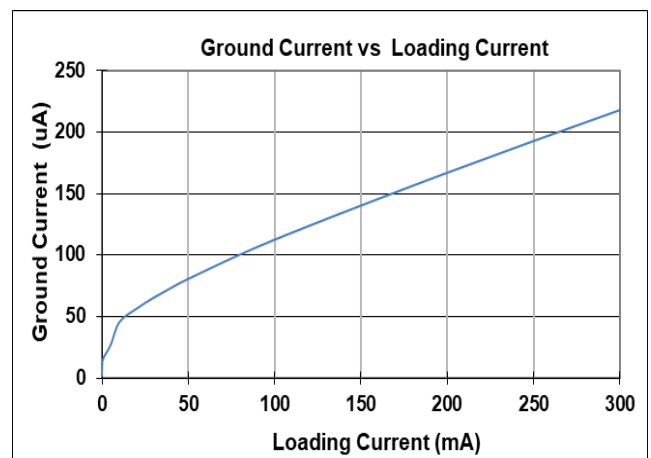
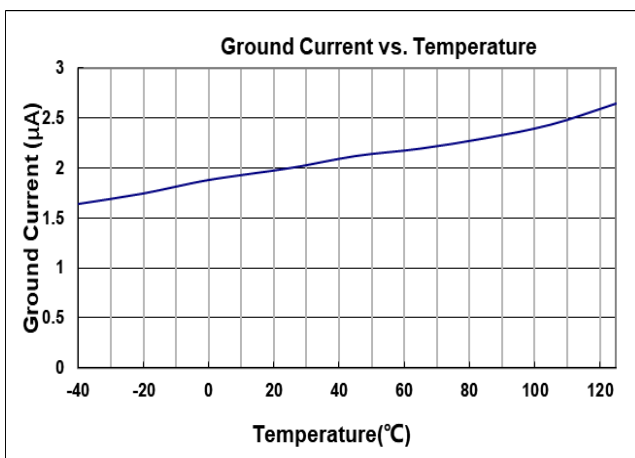
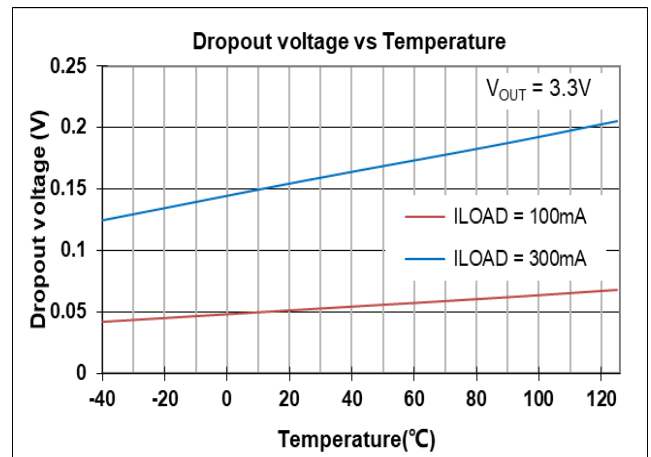
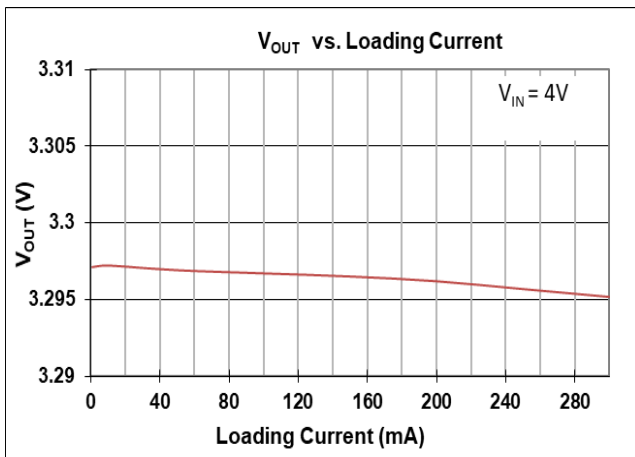
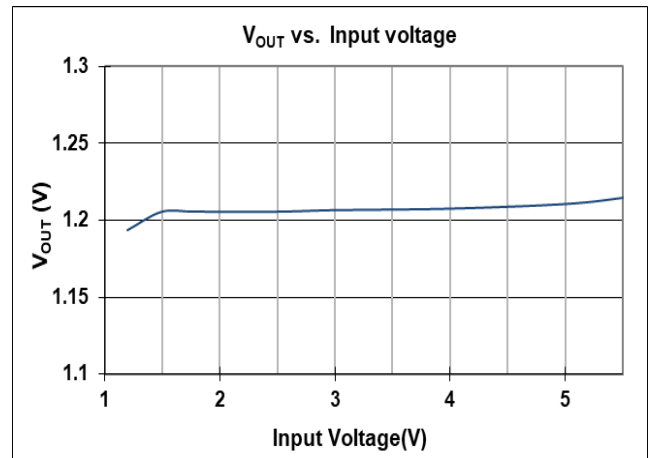
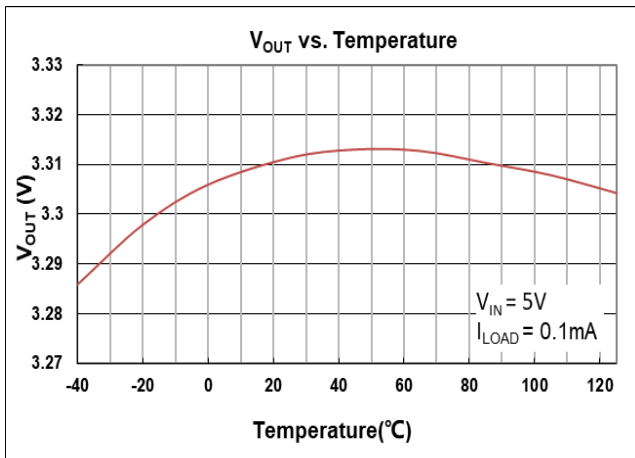
参数	符号	测试条件	最小值	典型值	最大值	单位	
输入电压	$V_{IN}$		1.2	--	5.5	V	
输出电压精准度		$I_{LOAD} = 0.1mA$	-2		2	%	
SNS 输入电流	$I_{SNS}$	$SNS = V_{OUT}$		0.5		$\mu A$	
Dropout 电压 ( $I_{LOAD} = 300mA$ ) (Note 3)	$V_{DROP\_3V}$	$V_{OUT} \geq 3V$		0.18		V	
	$V_{DROP\_2.8V}$	$V_{OUT} = 2.8V$		0.23			
	$V_{DROP\_2.5V}$	$V_{OUT} = 2.5V$		0.23			
	$V_{DROP\_1.8V}$	$V_{OUT} = 1.8V$		0.28			
	$V_{DROP\_1.5V}$	$V_{OUT} = 1.5V$		0.36			
	$V_{DROP\_1.2V}$	$V_{OUT} = 1.2V$		0.45			
静态电流	$I_Q$	$I_{LOAD} = 0mA$		2		$\mu A$	
关闭电流	$I_{SD}$	$V_{EN} = 0V$ , $V_{OUT} = 0V$		0.1	0.5	$\mu A$	
使能电压阈值	$V_{IH}$	EN Rising	1.0			V	
	$V_{IL}$	EN Falling			0.4		
EN 输入电流	$I_{EN}$	$V_{EN} = 5V$		10	100	nA	
输入电压调整率	$\Delta LINE$	$I_{LOAD} = 30mA$ , $1.5V \leq V_{IN} \leq 5.5V$ or $(V_{OUT} + 0.2V) \leq V_{IN} \leq 5.5V$		0.2		%	
负载电压调整率	$\Delta LOAD$	$10mA \leq I_{LOAD} \leq 0.3A$		0.2		%	
输出电流限流值	$I_{LIM}$	$V_{OUT} = 0V$	301	600		mA	
电源抑制比 ( $I_{LOAD} = 5mA$ )	PSRR	$V_{OUT} = 1.2V$ , $V_{IN} = 2V$	$f = 100Hz$	--	80	--	dB
			$f = 1kHz$	--	75	--	
输出电流噪声 ( $BW = 10Hz$ to $100kHz$ , $C_{OUT} = 1\mu F$ .)		$V_{IN} = 3.5V$ $I_{LOAD} = 0.1A$	$V_{OUT} = 1.2V$	--	80	--	$\mu V_{RMS}$
			$V_{OUT} = 2.8V$	--	120	--	
过温度关断温度	$T_{SD}$	$I_{LOAD} = 10mA$		--	155	--	$^\circ C$
过温度关断迟滞	$\Delta T_{SD}$			--	15	--	$^\circ C$
放电电阻	$R_{DC}$	$EN = 0V$ , $V_{OUT} = 0.1V$	--	30	--	$\Omega$	

**Note 1.** 任何超过“最大耐压值”的应用可能会导致芯片遭受永久性损坏。这些是额定最大耐压值，仅表示在这个范围内芯片不会损伤，但不保证所有性指标都正常，在任何超过“最大耐压值”的场合使用，都可能导致芯片永久性损坏。在接近或等于最大耐压值情况下使用，可能会影响产品可靠性。

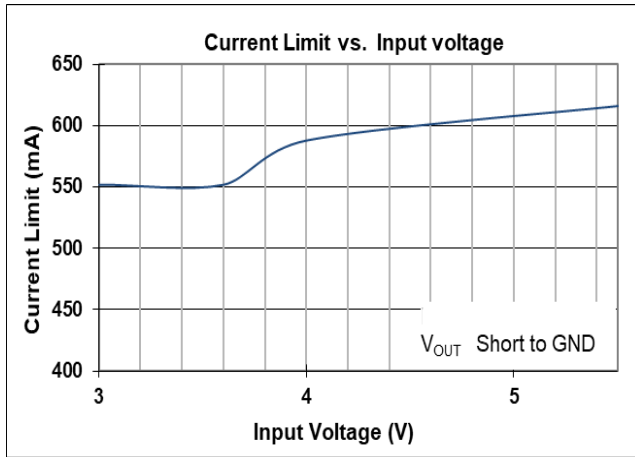
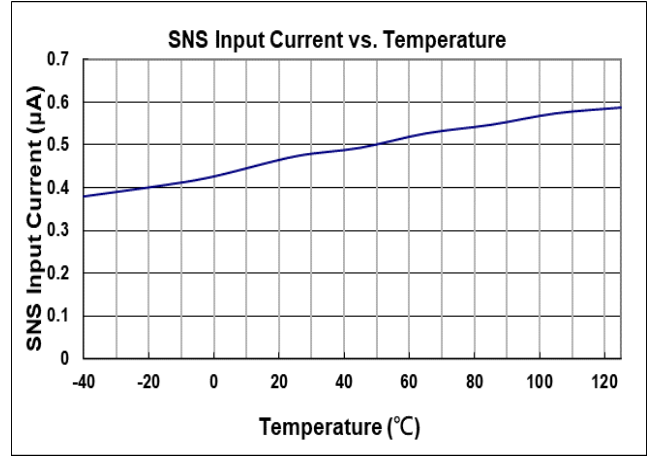
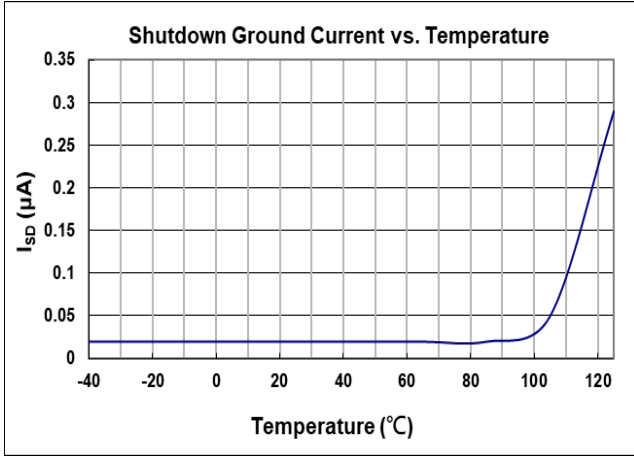
**Note 2.**  $\theta_{JA}$  测量条件： $T_A = 25^\circ C$ ，使用 EVB 板。

**Note 3.**  $V_{DROP} = V_{IN} - V_{OUT}$  ( $V_{OUT}$  达到 98%标准值)。

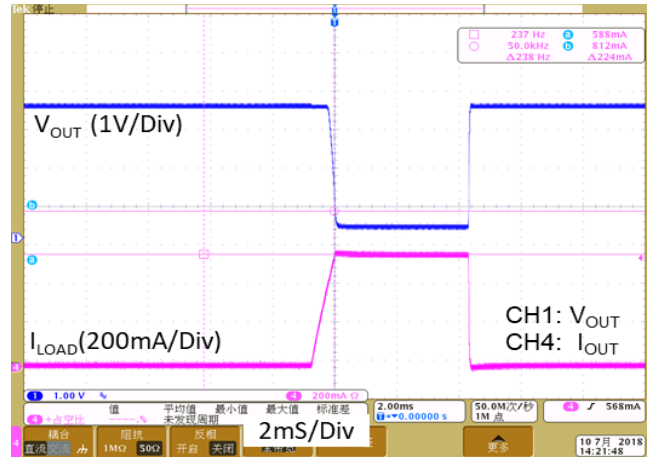
典型电气特性



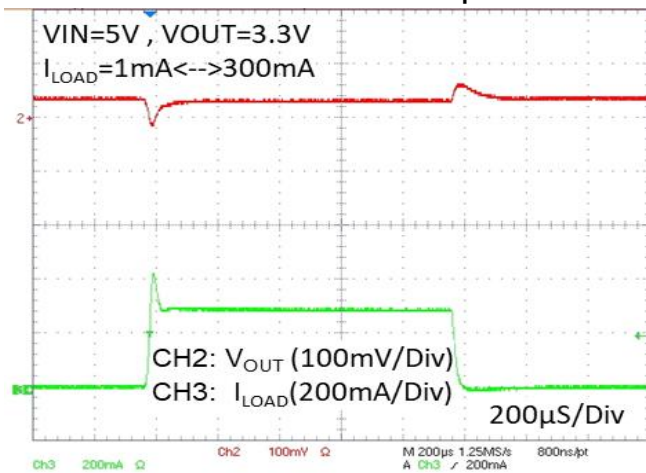




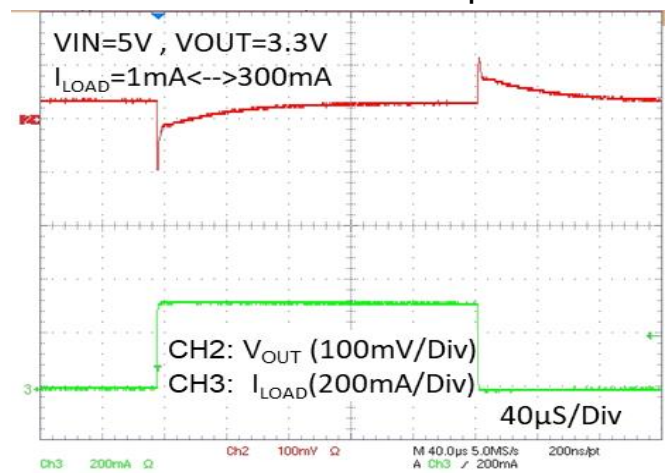
**Current Limit Response**



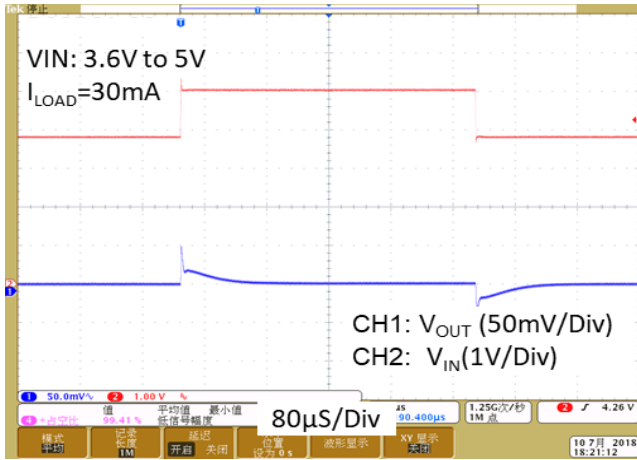
**Load Transient Response I**



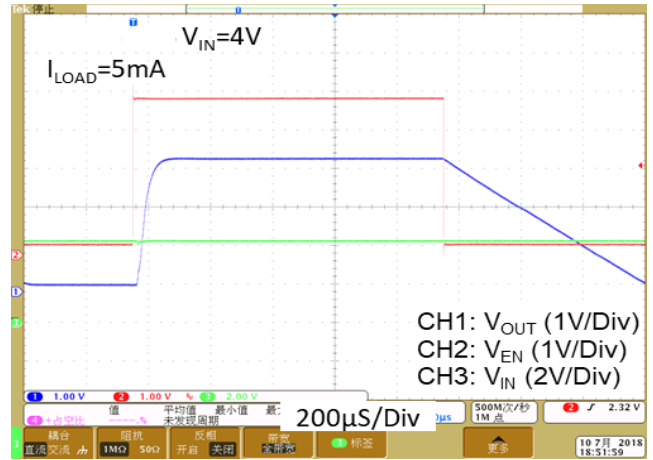
**Load Transient Response II**



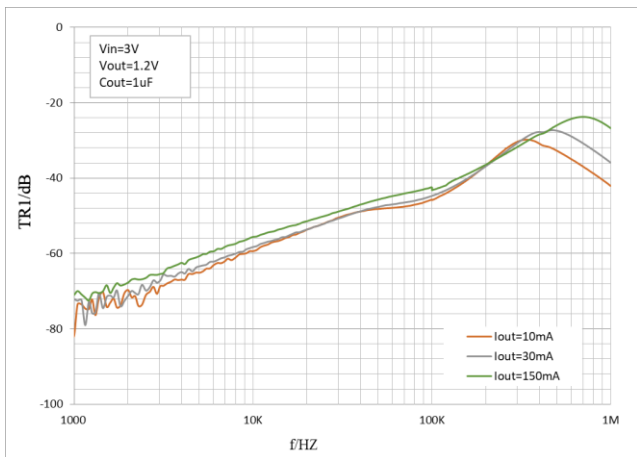
Line Transient Response



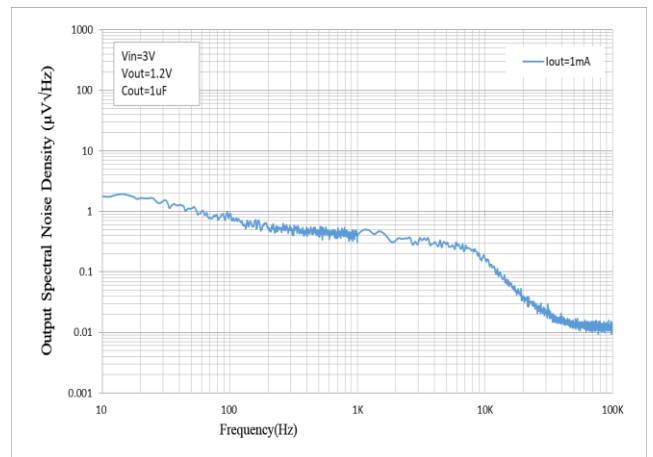
V<sub>OUT</sub> Turn On/Off by EN



PSRR vs. Frequency



Noise Density Spectrum



## 应用指导

### 输入和输出电容

XC6228DXX2VR-G(MS)系列产品应用, 需要选择合适的输入电容和输出电容, 以确保产品应用获得稳定可靠的性能。使用 1uF 或者更大容值的输入电容, 并将其靠近 IC 的VIN 和 GND pin 脚摆放。输出电容可选用 1mΩ以上 ESR (等效串联阻抗), 有效容值 1uF 至 22uF 的电容。并将输出电容靠近IC 的 V<sub>OUT</sub> 和 GND 脚摆放。增加输出电容的容值和降低ESR 能够提升电路的 PSRR 和瞬态响应能力。

### Dropout 电压

XC6228DXX2VR-G(MS)系列采用 PMOS 传输晶体管来实现低压差。当 (V<sub>IN</sub> - V<sub>OUT</sub>) 小于 (V<sub>DRO</sub>)时, PMOS 晶体管处于线性工作区域, 输入至输出阻抗即为 PMOS 的 R<sub>DS(ON)</sub>, 在此状态下, PMOS 等效于一颗电阻, V<sub>DRO</sub> 和输出电流近似成比例。和其他线性电压转换器一样, XC6228DXX2VR-G(MS) 系列的PSRR和瞬态响应能力会随着 (V<sub>IN</sub> - V<sub>OUT</sub>)压差接近V<sub>DRO</sub> 而下降。

## Layout 注意事项

将输入电容、输出电容和 LDO 放置在 PCB 的同一面, 并尽量将电容器靠近 IC 的输入输出脚摆放, 可实现电路最佳性能。输入电容和输出电容的接地连接必须拉回到 XC6228DXX2VR-G(MS) 的接地引脚, 并使用短而粗的铺线连接。避免使用长走线、窄走线、或者通过过孔走线, 这些会增加寄生电感和电阻, 导致电路性能变差, 特别是在瞬态工作条件下。

### 电流限制功能

XC6228DXX2VR-G(MS)系列产品内部的电流限制器可持续监控及控制输出功率晶体管, 将输出电流限制至 600mA (典型值)。限流功能确保输出可以短路至地, 器件不会损坏。

### OTP (过温度保护)

当产品的结点温度超过 155°C (典型值) 时, XC6228DXX2VR-G(MS)会关闭P-MOS 关闭输出。当结点温度往回降大约 15°C 时, XC6228DXX2VR-G(MS)会重新自动重启工作。

### 热散功率

持续工作时, IC 的结点温度不应超过其额定值。最大的热散功率取决于 IC 封装的热阻、PCB 布图、周围气流速率以及结点和环境温度的差异。最大热散功率计算如下:

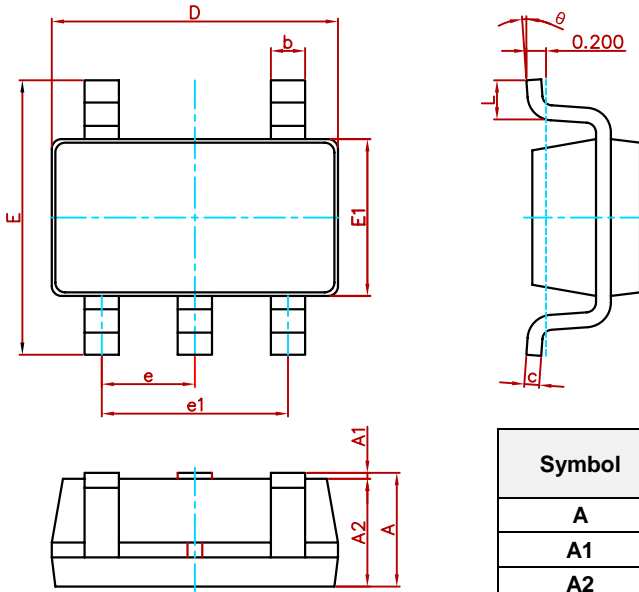
环温 T<sub>A</sub>=25°C, 使用 MSKSEMI PCB,

$$PD(\text{Max}) = (125^\circ\text{C} - 25^\circ\text{C}) / (200^\circ\text{C}/\text{W}) = 0.5\text{W}$$

热散功率(PD)等于输出电流和 LDO 上的压降的乘积, 计算公式如下:

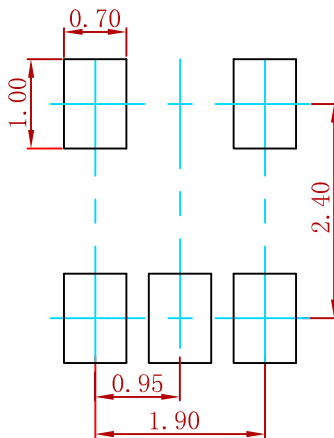
$$PD = (V_{IN} - V_{OUT}) \times I_{OUT}$$

**Package Outline Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	2.650	2.950	0.104	0.116
E1	1.500	1.700	0.059	0.067
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

**Suggested Pad Layout**



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.

## 订购信息

订单型号	封装形式	包装/数量
XC6228D122VR-G(MS)	SOT-23-5	盘装/3000pcs
XC6228D152VR-G(MS)	SOT-23-5	盘装/3000pcs
XC6228D182VR-G(MS)	SOT-23-5	盘装/3000pcs
XC6228D252VR-G(MS)	SOT-23-5	盘装/3000pcs
XC6228D282VR-G(MS)	SOT-23-5	盘装/3000pcs
XC6228D302VR-G(MS)	SOT-23-5	盘装/3000pcs
XC6228D332VR-G(MS)	SOT-23-5	盘装/3000pcs

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